

65 536-BIT (65 536-WORD BY 1-BIT) DYNAMIC RAM

DESCRIPTION

This is a family of 65 536-word by 1-bit dynamic RAMs, fabricated with the high performance N-channel silicongate MOS process, and is ideal for large-capacity memory systems where high speed, low power dissipation, and low costs are essential. The use of double-layer polysilicon process technology and a single-transistor dynamic storage cell privide high circuit density at reduced costs, and the use of dynamic circuitry including sense amplifiers assures low power dissipation. Multiplexed address inputs permit both a reduction in pins to the standard 16-pin package configuration and an increase in system densities. The M5K4164ANP operates on a 5V power supply using the on-chip substrate bias generator.

FEATURES

• High speed

Type name	Access time (max) (ns)	Cycle time (min) (ns)	Power dissipation (typ) (mW)
M5K4164ANP-12	120	220	175
M5K4164ANP-15	150	260	150

- Single 5V±10% supply
- Low standby power dissipation: 22mW (max)
- Low operating power dissipation: 300mW (max)
- Unlatched output enables two-dimensional chip selection and extended page boundary
- Early-write operation gives common I/O capability
- Read-modify-write, RAS-only refresh, and page-mode capabilities
- All input terminals have low input capaciatance and are directly TTL-compatible



- Output is three-state and directly TTL-compatible
- 128 refresh cycles every 2ms (16K dynamic RAMs M5K4116P, S compatible)
- CAS controlled output allows hidden refresh
- Output data can be held infinitely by CAS
- Interchangeable with Mostek's MK4564 and Motorola's MCM6665 in pin configuration

APPLICATION

Main memory unit for computers





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FUNCTION

The M5K4164ANP provides, in addition to normal read, write, and read-modify-write operations, a number of other functions, e.g., page mode, RAS-only refresh, and delayed-write. The input conditions for each are shown in Table 1.

Table 1 Input conditions for each mode

			Ing	outs			Output		
Operation	RAS	CAS	W	D	Row address	Column address	Q	Refresh	Remarks
Read	ACT	ACT	NAC	DNC	APD	APD	VLD	YES	Page mode
Write	ACT	ACT	ACT	VLD	APD	APD	OPN	YES	identical except
Read-modify-write	ACT	ACT	ACT	VLD	APD	APD	VLD	YES	refresh is NO.
RAS-only refresh	ACT	NAC	DNC	DNC	APD	DNC	OPN	YES	
Hidden refresh	ACT	ACT	DNC	DNC	APD	DNC	VLD	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN.	NO	

Note: ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, APD : applied, OPN : open.

SUMMARY OF OPERATIONS

Addressing

To select one of the 65536 memory cells in the M5K4164ANP the 16-bit address signal must be multiplexed into 8 address signals, which are then latched into the on-chip latch by two externally-applied clock pulses. First, the negative-going edge of the row-address-strobe pulse (\overline{RAS}) latches the 8 row-address bits; next, the negative-going edge of the column-address-strobe pulse (\overline{CAS}) latches the 8 column-address bits. Timing of the \overline{RAS} and \overline{CAS} clocks can be selected by either of the following two methods:

- 1. The delay time from \overrightarrow{RAS} to \overrightarrow{CAS} t_d (RAS-CAS) is set between the minimum and maximum values of the limits. In this case, the internal \overrightarrow{CAS} control signals are inhibited almost until t_d(RAS-CAS) max ('gated $\overrightarrow{CAS'}$ operation). The external \overrightarrow{CAS} signal can be applied with a margin not affecting the on-chip circuit operations, e.g. access time, and the address inputs can be easily changed from row address to column address.
- 2. The delay time $t_{d(RAS-CAS)}$ is set larger than the maximum value of the limits. In this case the internal inhibition of \overline{CAS} has already been released, so that the internal \overline{CAS} control signals are controlled by the externally applied \overline{CAS} , which also controls the access time.

Data Input

Data to be written into a selected cell is strobed by the later of the two negative transistons of \overline{W} input and \overline{CAS} input. Thus when the \overline{W} input makes its negative transition prior to \overline{CAS} input (early write), the data input is strobed by \overline{CAS} , and the negative transition of \overline{CAS} is set as the reference point for set-up and hold times. In the read-write or read-modify-write cycles, however, when the \overline{W} input makes its negative transition after \overline{CAS} , the \overline{W} negative transition is set as the reference point for setup and hold times.

Data Output Control

The output of the M5K4164ANP is in the high-impedance state when \overline{CAS} is high. When the memory cycle in progress is a read, read-modify-write, or a delayed-write cycle, the data output will go from the high-impedance state to the active condition, and the data in the selected cell will be read. This data output will have the same polarity as the input data. Once the output has entered the active condition, this condition will be maintained until \overline{CAS} goes high, irrespective of the condition of \overline{RAS} .

The output will remain in the high-impedance state throughout the entire cycle in an early-write cycle.

These output conditions, of the M5K4164ANP, which can readily be changed by controlling the timing of the write pulse in a write cycle, and the width of the \overline{CAS} pulse in a read cycle, offer capabilities for a number of applications, as follows.

1. Common I/O Operation

If all write operations are performed in the early-write mode, input and output can be connected directly to give a common I/O data bus.

2 Data Output Hold

The data output can be held between read cycles, without lengthening the cycle time. This enables extremely flexible clock-timing settings for \overline{RAS} and \overline{CAS} .



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3. Two Methods of Chip Selection

Since the output is not latched, \overline{CAS} is not required to keep the outputs of selected chips in the matrix in a highimpedance state. This means that \overline{CAS} and/or \overline{RAS} can both be decoded for chip selection.

4. Extended-Page Boundary

By decoding \overline{CAS} , the page boundary can be extended beyond the 256 column locations in a single chip. In this case, \overline{RAS} must be applied to all devices.

Page-Mode Operation

This operation allows for multiple-column addressing at the same row address, and eliminates the power dissipation associated with the negative-going edge of \overline{RAS} , because once the row address has been strobed, \overline{RAS} is maintained. Also, the time required to strobe in the row address for the second and subsequent cycles is eliminated, thereby decreasing the access and cycle times.

Refresh

Each of the 128 rows ($A_0 \sim A_6$) of the M5K4164ANP must be refreshed every 2 ms to maintain data. The methods of refreshing for the M5K4164ANP are as follows.

1. Normal Refresh

Read cycle and Write cycle (early write, delayed write or read-modify-write) refresh the selected row as defined by the low order (\overline{RAS}) addresses. Any write cycle, of course, may change the state of the selected cell. Using a read, write, or read-modify-write cycle for refresh is not recommended for systems which utilize "write-OR" outputs since output bus contention will occur.

2. RAS Only Refresh

A RAS-only refresh cycle is the recommended technique for most applications to provide for data retention. A RAS-only refresh cycle maintains the output in the high-impedance state with a typical power reduction of 20% over a read or write cycle.

3. Hidden Refresh

A feature of the M5K4164ANP is that refresh cycles may be performed while maintaining valid data at the output pin by extending the \overline{CAS} active time from a previous memory read cycle. This feature is referred to as hidden refresh.

Hidden refresh is performed by holding \overline{CAS} at V_{1L} and taking \overline{RAS} high and after a specified precharge period, executing a \overline{RAS} -only cycling, but with \overline{CAS} held low.

The advantage of this refresh mode is that data can be held valid at the output data port indefinitely by leaving the \overline{CAS} asserted. In many applications this eliminates the need for off-chip latches.

Power Dissipation

Most of the circuitry in the M5K4164ANP is dynamic, and most of the power is dissipated when addresses are strobed. Both \overline{RAS} and \overline{CAS} are decoded and applied to the M5K4164ANP as chip-select in the memory system, but if \overline{RAS} is decoded, all unselected devices go into stand-by independent of the \overline{CAS} condition, minimizing system power dissipation.

Power Supplies

The M5K4164ANP operates on a single 5V power supply.

A wait of some $500\mu s$ and eight or more dummy cycles is necessary after power is applied to the device before memory operation is achieved.



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ABSOLUTE MAXIMUM RATINGS

Symbol	Paramater	Conditions	Limits	Unit
Vcc	Supply voltage		-1-7	V
VI	Input voltage	With respect to V _{SS}	-1~7	V
Vo	Output voltage		-1~7	V
10	Output current		50	mA
Pd	Power dissipation	Ta=25°C	700	mW
Topr	Operating free-air temperature range		0~70	°C
Tstg	Storage temperature range		- 65 ~ 150	°C

RECOMMENDED OPERATING CONDITIONS ($Ta = 0 \sim 70^{\circ}C$, unless otherwise noted) (Note. 1)

Symbol	Parameter		Limits				
Symbol	Farameter	Min	Nom	Max	Unit		
Vcc	Supply voltage	4.5	5	5.5	V		
Vss	Supply voltage	0	0	0	V		
VIH	High-level input voltage, all inputs	2.4		6.5	v		
VIL	Low-level input voltage, all inputs	- 2		0.8	V		

Note 1: All voltage values are with respect to V_{SS}

$\label{eq:construction} \textbf{ELECTRICAL CHARACTERISTICS} (\ \texttt{Ta}=0~70^\circ\texttt{C} \ , \ \texttt{V}_{\texttt{CC}}=5 \texttt{V} \pm 10\%, \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{unless otherwise noted} (\texttt{Note. 2}) \ \texttt{Note. 2} \ \texttt{V}_{\texttt{CC}}=5 \texttt{V} \pm 10\%, \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{unless otherwise noted} (\texttt{Note. 2}) \ \texttt{V}_{\texttt{CC}}=5 \texttt{V} \pm 10\%, \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{unless otherwise noted} (\texttt{Note. 2}) \ \texttt{Note. 2} \ \texttt{V}_{\texttt{CC}}=5 \texttt{V} \pm 10\%, \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{unless otherwise noted} (\texttt{Note. 2}) \ \texttt{V}_{\texttt{CC}}=5 \texttt{V} \pm 10\%, \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{unless otherwise noted} (\texttt{Note. 2}) \ \texttt{V}_{\texttt{CC}}=5 \texttt{V} \pm 10\%, \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{unless otherwise noted} (\texttt{Note. 2}) \ \texttt{V}_{\texttt{CC}}=5 \texttt{V} \pm 10\%, \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{Unless otherwise noted} (\texttt{Note. 2}) \ \texttt{V}_{\texttt{SS}}=0\texttt{V}, \ \texttt{Unless otherwise noted} (\texttt{SS}=0\texttt{V}) \ \texttt{U}_{\texttt{SS}}=0\texttt{V}, \ \texttt{U}_{\texttt$

Symbol	Decementer		Test and delays		Limits		
Symbol	Parameter		Test conditions	Min	Тур	Max	Unit
V _{OH}	High-level output voltage		I _{OH} = -5mA	2.4		Vcc	V
VOL	Low-level output voltage		I _{OL} =4.2mA	0		0.4	V
loz	Off-state output current		Q floating $0V \leq V_{OUT} \leq 5.5V$			10	μA
lj.	Input current		$0V \leq V_{IN} \leq 6.5V$, All other pins = $0V$	- 10		10	μA
CC1(AV)	Average supply current from Vcc.	M5K4164ANP-12	RAS, CAS cycling			50	mΑ
(CUT(AV)	operating (Note 3, 4)	M5K4164ANP-15	$t_{CR} = t_{CW} = min \text{ output open}$			45	
I CC2	Supply current from V _{CC} , standb	/	RAS = VIH output open			4	mA
CC3(AV)	Average supply current from Vcc	M5K4164ANP-12	RAS cycling CAS = VIH			40	mA
CC3(AV)	refreshing (Note 3)	M5K4164ANP-15	t _{C(REF)} = min, output open			35	
1	Average supply current from V _{CC} ,	M5K4164ANP-12	RAS = VIL, CAS cycling			40	mA
CC4(AV)	page mode (Note 3, 4)	M5K4164ANP-15	t CPG = min, output open		1	35	
C _{I (A)}	Input capacitance, address inputs	Mar, an <u>, a</u> <u>n, c, n, c, c, c</u>				5	pF
C _{1 (D)}	Input capacitance, data input		VI=VSS			5	pF
C _{1(W)}	Input capacitance, write control in	put	f=1MHz			7	pF
CI (RAS)	Input capacitance, RAS input		V ₁ =25mVrms			10	pF
CI (CAS)	Input capacitance, CAS input					10	pF
Co	Output capacitance		$V_0 = V_{SS}, f = 1 M H z, V_1 = 25 m V rms$	1	1	7	pF

Note 2: Current flowing into an IC is positive , out is negative.

3: ICC1(AV), ICC3(AV), and ICC4(AV) are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.

4: ICC1(AV) and ICC4(AV) are dependent on output loading. Specified values are obtained with the output open.



M5K4164ANP-12, -15

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TIMING REQUIREMENTS (For Read, Write, Read-Modify-Write, Refresh, and Page-Mode Cycle)

($Ta=0\sim70^\circ C$, $~V_{CC}=5V\pm10\%,~V_{SS}=0V$, unless otherwise noted, See notes 5, 6 and 7)

			M5K416	4ANP-12	M5K4164	ANP-15	Unit
Parameter			Lir	mits	Limits		
		Symbol	Min	Max	Min	Max	
Refresh cycle time		t _{REF}		2		2	ms
RAS high pulse width		t _{RP}	90		100		ns
RAS low pulse width		t _{RAS}	120	10000	150	10000	ns
CAS low pulse width		t _{CAS}	60	∞	75	· ∞	ns
CAS high pulse width	(Note 8)	t _{CPN}	30		35		ns
CAS hold time after RAS		t _{CSH}	120		150		ns
RAS hold time after CAS		t _{RSH}	60		75		ns
Delay time, CAS to RAS	(Note 9)	t _{CRP}	- 20		-20		ns
Delay time, RAS to CAS	(Note 10)	t _{RCD}	25	60	30	75	ns
Row address setup time before RAS	-	t _{ASR}	0		0		ns
Column address setup time before \overline{CA}	<u>s</u>	t _{ASC}	0		0		ns
Row address hold time after RAS		t _{RAH}	15		20		ns
Column address hold time after \overline{CAS}		t _{CAH}	20		25		ns
Column address hold time after \overline{RAS}		t _{AR}	90		95		ns
Transition time		t _T	3	35	3	35	ns
	Refresh cycle time RAS high pulse width RAS low pulse width CAS low pulse width CAS high pulse width CAS high pulse width CAS hold time after RAS RAS hold time after CAS Delay time, CAS to RAS Delay time, RAS to CAS Row address setup time before RAS Column address setup time before CA Row address hold time after CAS Column address hold time after RAS Column address hold time after RAS Column address hold time after RAS	Refresh cycle time RAS high pulse width RAS low pulse width CAS low pulse width CAS high pulse width CAS high pulse width CAS high pulse width CAS hold time after RAS RAS hold time after CAS Delay time, CAS to RAS (Note 9) Delay time, RAS to CAS (Note 10) Row address setup time before RAS Column address hold time after RAS Column address hold time after CAS Column address hold time after RAS Column address hold time after RAS	Symbol Refresh cycle time t REF RAS high pulse width t RP RAS low pulse width t RAS CAS low pulse width t CAS CAS high pulse width t CAS CAS high pulse width t CAS CAS high pulse width t CAS CAS hold time after RAS t CSH RAS hold time after RAS t CSH Delay time, CAS to RAS (Note 9) t CRP Delay time, RAS to CAS (Note 10) t RCD Row address setup time before RAS t ASR Column address hold time after RAS t CAH Column address hold time after RAS t CAH	Parameter Alternative Symbol Lit Refresh cycle time t REF Min Refresh cycle time t REF RAS high pulse width t RP 90 RAS low pulse width t RAS 120 CAS low pulse width t CAS 60 CAS high pulse width t CAS 60 CAS high pulse width t Note 8) t CPN 30 CAS hold time after RAS t CSH 120 RAS hold time after CAS t RSH 60 Delay time, CAS to RAS (Note 9) t CRP -20 Delay time, RAS to CAS (Note 10) t RCD 25 Row address setup time before RAS t ASR 0 Column address hold time after RAS t ASC 0 Row address hold time after RAS t CAH 15 Column address hold time after RAS t CAH 20 Column address hold time after RAS t AR 90	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c } Parameter & Alternative \\ Symbol & Imits & Limits \\ \hline Min & Max & Min & Max \\ \hline Min & Max & Min & Max \\ \hline Min & Max & Min & Max \\ \hline Min & Max & Min & Max \\ \hline Min & Max & Min & Max \\ \hline Min & Max & Min & Max \\ \hline Max & 1 \\ \hline RAS high pulse width & t \\ RAS & 1 \\ RAS & low pulse width & t \\ RAS & 120 & 10000 & 150 & 10000 \\ \hline \hline RAS low pulse width & t \\ CAS & 60 & \infty & 75 & \infty \\ \hline \hline CAS high pulse width & (Note 8) & t \\ CPN & 30 & 35 & \hline \hline CAS hold time after RAS & t \\ CSH & 120 & 150 & \hline \hline CAS hold time after RAS & t \\ Delay time, \hline CAS to RAS & (Note 9) & t \\ CRP & -20 & -20 & \hline \hline Delay time, \hline RAS to CAS & (Note 10) & t \\ Row address setup time before \hline RAS & t \\ Column address hold time after RAS & t \\ Column address hold time after \hline CAS & t \\ RAS hold time after RAS & t \\ Column address hold time after \hline CAS & t \\ RAS hold time after RAS & t \\ Column address hold time after \hline CAS & t \\ Row address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ Column address hold time after \hline CAS & t \\ CAR & 0 & 0 \\ \hline COlumn address hold time after \hline CAS & t \\ CAR & 0 & 0 \\ \hline COLUMN address hold time after \hline CAS & t \\ CAR & 0 & 0 \\ \hline CAR & $

Note 5: An initial pause of 500 µs is required after power-up followed by any eight RAS or RAS/CAS cycles before proper device operation is achieved.

The switching characteristics are defined as $t_{THL} = t_{TLH} = 5ns$. 6:

7: Reference levels of input signals are VIH min, and VIL max. Reference levels for transition time are also between VIH and VIL.

8: Except for page-mode.

9: td(CAS.RAS) requirement is only applicable for RAS/CAS cycles preceeded by a CAS only cycle (i.e., For systems where CAS has not been decoded with RAS.) 10: Operation within the td (RAS-CAS) max limit insures that ta (RAS) max can be met. td (RAS-CAS) max is specified reference point only; if td (RAS-CAS) is greater than the specified td (RAS-CAS) max limit, then access time is controlled exclusively by ta(CAS).

td (ras-cas)min = th (ras-ra)min + 2t thL(t tLH) + t su(ca-cas)min.

SWITCHING CHARACTERISTICS (Ta = $0 \sim 70^{\circ}$ C, V_{CC} = $5V \pm 10\%$, V_{SS} = 0V, unless otherwise noted) **Read Cycle**

Symbol				M5K416	4ANP-12	M5K4164ANP-15		
	Parameter		Alternative	Lir	nits	Limi	Limits	
	1	Symbol	Symbol	Min	Max	Min	Max	
t _{CR}	Read cycle time		t _{RC}	220		260		ns
tsu (R-CAS)	Read setup time before CAS		t _{RCS}	0		0		ns
th (CAS-R)	Read hold time after CAS	(Note 11)	t _{RCH}	0		0		ns
th(RAS-R)	Read hold time after RAS	(Note 11)	t _{RRH}	10		20		ns
tdis (CAS)	Output disable time	(Note 12)	t _{OFF}	0	35	0	40	ns
ta (CAS)	CAS access time	(Note 13)	t _{CAC}		60		75	ns
ta (RAS)	RAS access time	(Note 14)	t _{RAC}		120		150	ns

Note 11: Either th (RAS-R) or th (CAS-R) must be satisfied for a read cycle.

tdis (CAS)max defines the time at which the output achieves the open circuit condition and is not reference to VOH or VOL. Note 12:

Note 13:

This is the value when td (RAS-CAS) \geq td (RAS-CAS)max. Test conditions : Load = 2 T L, C_L = 100 pF. This is the value when td (RAS-CAS) \geq td (RAS-CAS) will increase by the amount that Note 14: td (RAS-CAS) exceeds the value shown. Test conditions ; Load = 2T TL, C_L = 100pF

Write Cycle

				M5K	4164ANP-12	M5K4164	ANP-15	
Symbol	Parameter		Alternative	Limits		Limits		Unit
			Symbol	Min	Max	Min	Max	1
t _{cw}	Write cycle time		t _{RC}	220		260		ns
tsu(w-CAS)	Write setup time before CAS	(Note 17).	twcs	-5		-10		ns
th _(CAS-W)	Write hold time after CAS		t _{WCH}	40		45		ns
th (RAS-W)	Write hold time after RAS		t _{WCR}	90		95		ns
th (w-RAS)	RAS hold time after write		t _{RWL}	40		45		ns
th (w-cas)	CAS hold time after write		t _{cwL}	40		45		ns
tw(w)	Write pulse width		twp	40		45		ns
tsu (D-CAS)	Data-in setup time before CAS		t _{DS}	0		0		ns
th (CAS-D)	Data-in hold time after CAS		t _{DH}	40		45		ns
th (RAS-D)	Data-in hold time after RAS		t _{DHR}	90		95		ns



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	Parameter			M5K4164ANP-12		M5K416	4ANP-15	Unit
Symbol			Alternative	Li	mits	Limits		
			Symbol	Min	Max	Min	Max	1
t _{CRW}	Read-write cycle time	(Note 15)	tRWC	245		295		
tormw	Read-modify-write cycle time	(Note 16)	t RMWC	265		310		
th (w-RAS)	RAS hold time after write		t _{RWL}	40		45		ns
th (w-CAS)	CAS hold time after write		t _{CWL}	40		45		
tw(w)	Write pulse width		twp	40		45		ns
tsu (R-CAS)	Read setup time before CAS		t _{RCS}	0		. 0		ns
td (RAS-W)	Delay time, RAS to write	(Note 17)	t _{RWD}	100		120		ns
td (CAS-W)	Delay time, CAS to write	(Note 17)	t _{CWD}	40		60		ns
tsu(D-W)	Data-in setup time before write		t _{DS}	0	·	0		
th (w-D)	Data-in hold time after write		t _{DH}	40		45		ns
tdis (CAS)	Output disable time		t _{OFF}	0	35	0	40	ns
ta (CAS)	CAS access time	(Note 13)	t _{CAC}		60		75	ns
ta (RAS)	RAS access time	(Note 14)	t _{RAC}		120		100	ns

Read-Write and Read-Modify-Write Cycles

Note 15: $t_{CRW}min$ is defined as $t_{CRW}min = td_{(RAS-W)} + th_{(W-RAS)} + tw_{(RASH)} + 3t_{TLH}(t_{THL})$

16: t_{CRMW} min is defined as t_{CRMW} min = $t_a (RAS)max + th (W-RAS) + tw (RAS H) + 3t_{TLH}(t_{THL})$

17: tsu (w-cas), td (RAS-w), and td (cas-w) do not define the limits of operation, but are included as electrical characteristics only.

When tsu (w-cAs)≥tsu (w-cAs)min, an early-write cycle is performed, and the data output keeps the high-impedance state.

When td (RAS-w)≥td (RAS-w)min, and td (CAS-w)≥tsu (w-CAS)min a read-write cycle is performed, and the data of the selected address will be read out on the data output.

For all conditions other than those described above, the condition of data output (at access time and until CAS goes back to VIH) is not defined.

Page-Mode Cycle

			M5K416	4ANP-12	M5K4164ANP-15		
Symbol	Parameter	Alternative	Lir	nits	Lin	Limits	
	Symbol	Min	Max	Min	Max	1	
t _{c PGR}	Page-mode read cycle time	t _{PC}	140		145		ns
t _{c PGW}	Page-Mode write cycle time	t _{PC}	140		145		ns
t _{c PGRW}	Page-Mode read-write cycle time	- 1	150		180		ns
t _{c pgrmw}	Page-Mode read-modify-write cycle time	-	170		195		ns
tw(CASH)	CAS high pulse width	t _{CP}	55		60		ns



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MITSUBISHI LSIs

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Read-Write and Read-Modify-Write Cycles

RAS-Only Refresh Cycle (Note 19)



MITSUBISHI LSIs

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Page-Mode Read Cycle



Page-Mode Write Cycle





65 536-BIT (65 536-WORD BY 1-BIT) DYNAMIC RAM



Hidden Refresh Cycle

